Package Drawing

Designator: ES

Type: 16-Contact QFN, 3 mm × 3 mm, 0.75 mm thickness, with Exposed Thermal Pad

For Reference Only – Not for Tooling Use

(Reference Allegro DWG-0000222 Rev. 4 or JEDEC MO-220WEED)
Dimensions in millimeters
Exact case and lead configuration at supplier discretion within limits shown

C PCB Layout Reference View

E Standard Branding Reference View

Lines 1, 2, 3 = 4 characters

Line 1: Part Number
Line 2: 4 digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number

Pin 1 Dot top left
Center align

A Terminal #1 mark area.

B Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion).

C Reference land pattern layout (reference IPC7351 QFN50P300X300X80-17W4M);
All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5).

D Coplanarity includes exposed thermal pad and terminals.

E Branding scale and appearance at supplier discretion.

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